

## **Data sheet**

SAW filter GPS L2 & L5, Beidou B2

Series/type: B8889

Ordering code: B39122B8889P810

Date: April 09, 2019

Version: 2.1

DCN: 80-PA243-101 Rev. B

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RF360 Europe GmbH
A Qualcomm – TDK Joint Venture

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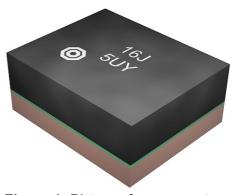
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#### 1 Application

- Low-loss RF GNSS L2/B2/L5 filter
- Simultaneous usage of GPS L2, BDS B2 and GPS L5 bands
- Usable passbands: 2.046 MHz for L2, 4.092 MHz for B2 and 20.46 MHz for GPS L5
- Very low insertion attenuation
- High out of band selectivity
- Filter impedance 50 Ω
- Unbalanced to unbalanced operation
- lacktriangle Matching network required for operation at 50  $\Omega$

#### 2 Features

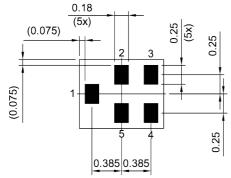
- Package size 1.1mm × 0.9 mm
- Package height 0.45 mm (max.)
- Approximate weight 1.2 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)



**Figure 1:** Picture of component with example of product marking.

### 3 Package

**BOTTOM VIEW** 



Pad and pitch tolerance ±0.05

## 4 Pin configuration

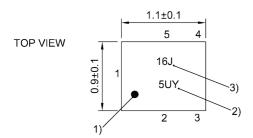
■ 1 Input

■ 4 Output

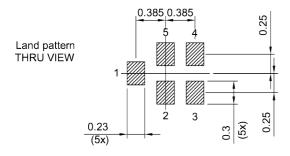
■ 2, 3, 5 Ground

SIDE VIEW





- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number



Landing pad tolerance -0.02

**Figure 2:** Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 18).

## 5 Matching circuit

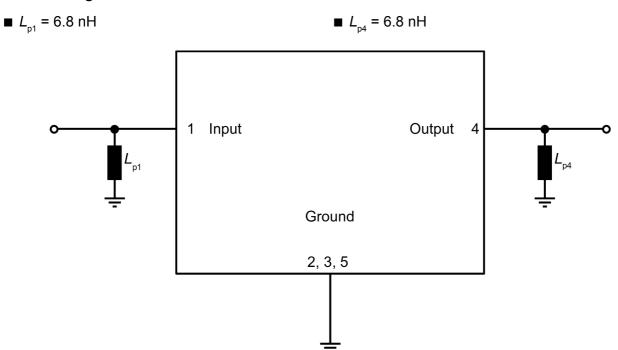


Figure 3: Schematic of matching circuit.



#### 6 Characteristics

Temperature range for specification  $T_{\rm SPEC} = -30~{\rm ^{\circ}C}~...~+85~{\rm ^{\circ}C}$  Input terminating impedance  $Z_{\rm IN} = 50~\Omega~//~6.8~{\rm nH^{1)}}$  Output terminating impedance  $Z_{\rm OUT} = 50~\Omega~//~6.8~{\rm nH^{1)}}$ 

Characteristics				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	<b>typ.</b> @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{SPEC}} \end{array}$	
Center frequency			f <sub>C</sub>	_	1197.42	_	MHz
Insertion attenuation			α				
	1166.22 1186.68	MHz		_	0.9 <sup>1)</sup>	1.5	
	1205.09 1209.19	MHz		_	1.0	1.3	dB
	1226.58 1228.62	MHz		_	1.4	2.6	dB
VSWR			VSWR				
@ input port	1166.22 1186.68	MHz		_	1.5	1.9	
	1205.09 1209.19	MHz		_	1.4	1.8	
	1226.58 1228.62	MHz		_	1.1	1.8	
@ output port	1166.22 1186.68	MHz		_	1.4	1.8	
	1205.09 1209.19	MHz		_	1.3	1.8	
	1226.58 1228.62	MHz		_	1.2	1.8	
Attenuation			α				
	698 748	MHz		46	49	_	dB
	777 798	MHz		44	48	_	dB
	807 915	MHz		41	45	_	dB
	925 960	MHz		41	45	_	dB
	1427 1463	MHz		30	42	_	dB
	1626.5 1660.5	MHz		20	32	_	dB
	1695 1785	MHz		25	40	_	dB
	1850 2025	MHz		30	45	_	dB
	2300 2400	MHz		36	42	_	dB
	2400 2483	MHz		33	39	_	dB
	2500 2690	MHz		33	37	_	dB
	3400 3800	MHz		29	33	_	dB
	5150 5925	MHz		22	26	_	dB

<sup>&</sup>lt;sup>1)</sup> Typical value averaged over indicated frequency range.



#### 7 **Maximum ratings**

Storage temperature	T <sub>STG</sub> <sup>2)</sup> = -40 °C +85 °C <sup>1)</sup>	
DC voltage	$ V_{DC} ^{3)} = 5.0 \text{ V}$	
ESD voltage	V <sub>ESD</sub> = 50 V	Machine model.
	V <sub>ESD</sub> <sup>5)</sup> = 300 V	Human body model.
	V <sub>ESD</sub> = 600 V	Charged device model.
Input power @ input port: 1166.22 1228.62 MHz	$P_{IN} = 5.0  \text{dBm}$	Continuous wave for 2000h @ 55 °C

<sup>1)</sup> Extended upperlimit: 96h@125°C acc. to IEC 60068-2-2 Bb.

<sup>2)</sup> Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.

<sup>168</sup>h Damp Heat Steady State acc. IEC 60068-2-67 Cy.

According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.

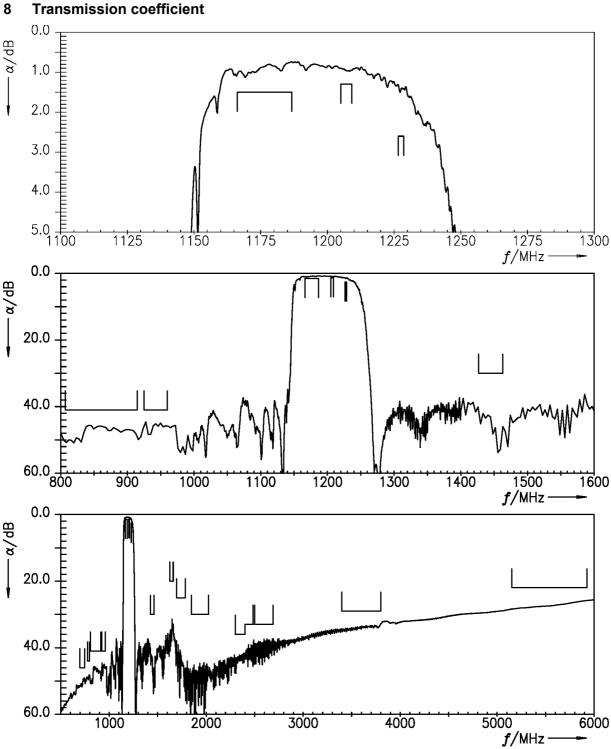
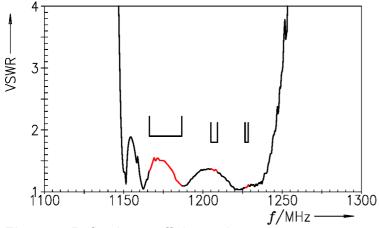


Figure 4: Attenuation .

#### 9 Reflection coefficients



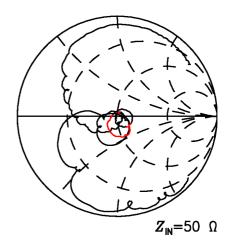
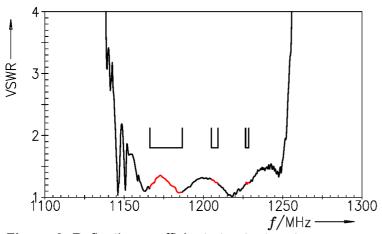


Figure 5: Reflection coefficient at input port.



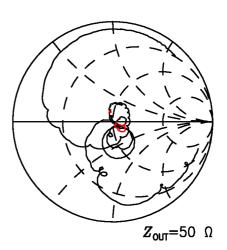
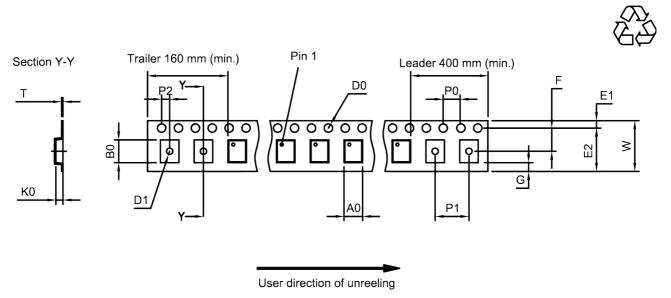


Figure 6: Reflection coefficient at output port.

## 10 Packing material

## 10.1 Tape



**Figure 7:** Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

$A_0$	1.02±0.05 mm	E <sub>2</sub>	6.25 mm (min.)	P <sub>1</sub>	2.0±0.1 mm
$B_0$	1.22±0.05 mm	F	3.5±0.05 mm	$P_2$	2.0±0.05 mm
D <sub>0</sub>	1.55±0.05 mm	G	_	Т	0.25±0.03 mm
D <sub>1</sub>	0.55±0.1 mm	K <sub>0</sub>	0.6±0.05 mm	W	8.0+0.3/-0.1 mm
E <sub>1</sub>	1.75 <sub>±0.1</sub> mm	P <sub>0</sub>	4.0±0.1 mm		

Table 1: Tape dimensions.

#### 10.2 Reel with diameter of 180 mm

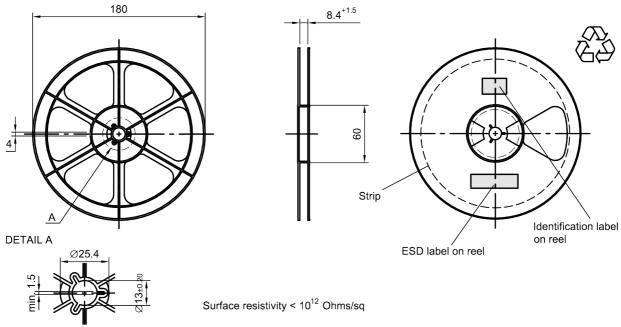


Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.

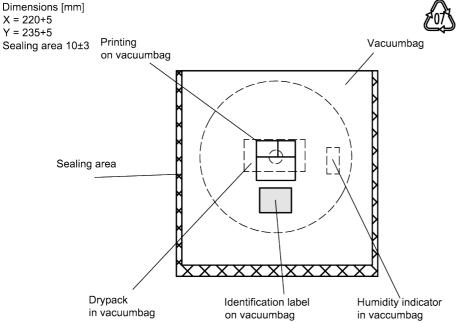


Figure 9: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

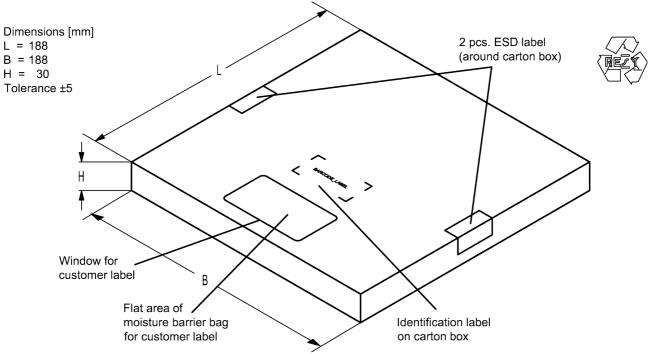


Figure 10: Drawing of folding box for reel with diameter of 180 mm.

#### 10.3 Reel with diameter of 330 mm

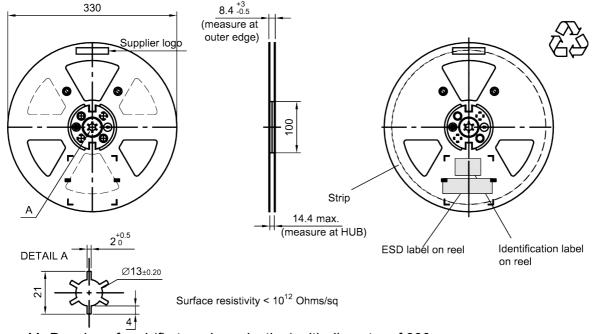


Figure 11: Drawing of reel (first-angle projection) with diameter of 330 mm.

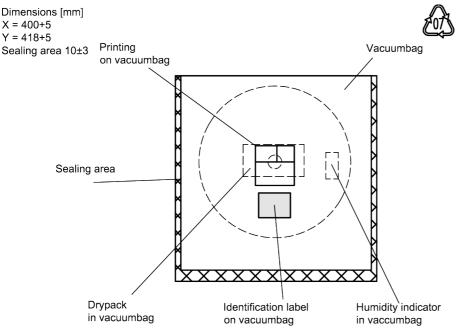


Figure 12: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

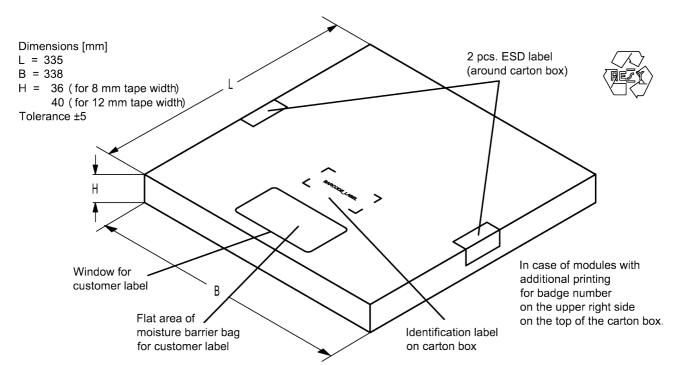


Figure 13: Drawing of folding box for reel with diameter of 330 mm.



#### 11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

#### ■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB1234xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

**16J** 1234 1 x  $32^2$  + 6 x  $32^1$  + 18 (=J) x  $32^0$ 1234

The BASE32 code for product type B8889 is 8NS.

#### ■ Lot number:

The last 5 digits of the lot number, 12345, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

อบา	_/	12345
$5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0$	=	12345

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	Н
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	Р
7	7	23	Q
8	8	24	R
9	9	25	S
10	Α	26	Т
11	В	27	V
12	С	28	W
13	D	29	Х
14	E	30	Y
15	F	31	Z

		Adopted BASE47 code for lot number				
Decimal	Base47	Decimal	Base47			
value	code	value	code			
0	0	24	R			
1	1	25	S			
2	2	26	Т			
3	3	27	U			
4	4	28	V			
5	5	29	W			
6	6	30	X			
7	7	31	Y			
8	8	32	Z			
9	9	33	b			
10	Α	34	d			
11	В	35	f			
12	С	36	h			
13	D	37	n			
14	E	38	r			
15	F	39	t			
16	G	40	V			
17	Н	41	\			
18	J	42	?			
19	K	43	{			
20	L	44	}			
21	M	45	<			
22	N	46	>			
23	Р					

**Table 2:** Lists for encoding and decoding of marking.

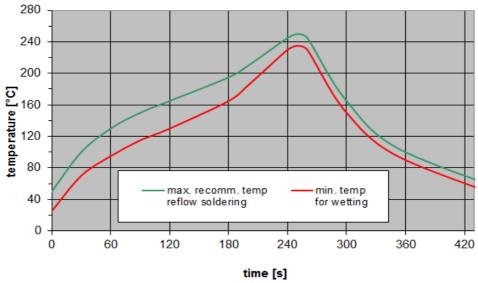


## 12 Soldering profile

The recommended soldering process is in accordance with IEC  $60068-2-58-3^{rd}$  edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature $T_{peak}$	250 °C +0/-5 °C
wetting temperature $T_{min}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature <i>T</i>	measured at solder pads

**Table 3:** Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 14:** Recommended reflow profile for convection and infrared soldering – lead-free solder.



#### 13 Annotations

### 13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

#### 13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

## 13.3 Ordering codes and packing units

Ordering code	Packing unit
B39122B8889P810	15,000 pcs
B39122B8889P810S 5	5,000 pcs

Table 4: Ordering codes and packing units.



#### 14 Cautions and warnings

### 14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <a href="https://www.rf360jv.com/orderingcodes">www.rf360jv.com/orderingcodes</a>.

#### 14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

#### 14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

#### 14.4 Package information

### Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

#### **Dimensions**

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

#### **Projection method**

Unless otherwise specified first-angle projection is applied.



#### 15 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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- 3. The warnings, cautions and product-specific notes must be observed.
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